© Copyri	al Composition Delight 2005. IPC, Bannock on al and Pan-American of the second	burn, Illinois. A	All rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the encompass	substance ses all low	s within the manufactu er level materials for v	rer listed i which the n	tem. Note: if nanufacturer	the item is an a has engineering	ssembly with lower responsibility.	
				Form Type Distribute					ials and Mfg Information					
Supplier Information														
Company name* Compan			npany unique ID			Unique ID Authority				Respons	Response Date*			
onsemi										2024-05	2024-05-06			
Contact Name Title - Co			e - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			Representative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Num	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Dat	e Versio	n	Manufacturing Site		Weight*	UOM	Unit Type	
	FDMF5	FDMF5085 100A		100A Gen4 Smart Power Stage in 5x6		2024-05-06			MY5		86.363754	mg	Each	
Manufacturing Proccess	Information													
Terminal Plating / Grid Array Material Terminal Base			Alloy	J-STD-020 MSI	L Rating	Peak Pro	cess Body	Temperati	are Max Time at Peal	K Temperat	ture Numbe	r of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy				1		260		С	30	secon	ids 3			
Comments														
level 1 - maximum time at peak	temperature during s	dering is 10-3	0 seconds											
For more information regardin	g material composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.80036	mg	Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Iron (Fe)	7439-89-6		0.1632	mg
			Supplier	Copper (Cu)	7440-50-8		6.6236	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0054	mg
Die	2.76287	mg	Supplier	Silicon (Si)	7440-21-3		2.7629	mg
Die Attach Solder	4.40103	mg	Supplier	Silver (Ag)	7440-22-4		0.11	mg
			А	Lead (Pb)	7439-92-1	7a	4.071	mg
			Supplier	Tin (Sn)	7440-31-5		0.2201	mg
Ероху	0.1	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.008	mg
			Supplier	Proprietary	Proprietary Data		0.009	mg
			Supplier	Bismaleimide	13676-54-5		0.027	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.001	mg
			Supplier	PTFE	9002-84-0		0.055	mg
Lead Frame	32.9996	mg	Supplier	Silver (Ag)	7440-22-4		1.65	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0396	mg
			Supplier	Iron (Fe)	7439-89-6		0.792	mg
			Supplier	Copper (Cu)	7440-50-8		30.4916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0264	mg
Mold Compound-Black	36.1	mg		Proprietary	proprietary data		2.888	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1805	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.0315	mg
lating	2.99983	mg	Supplier	Tin (Sn)	7440-31-5		2.9998	mg
Wire Bond - Cu	0.200061	mg	Supplier	Palladium (Pd)	7440-05-3		0.0036	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.1963	mg